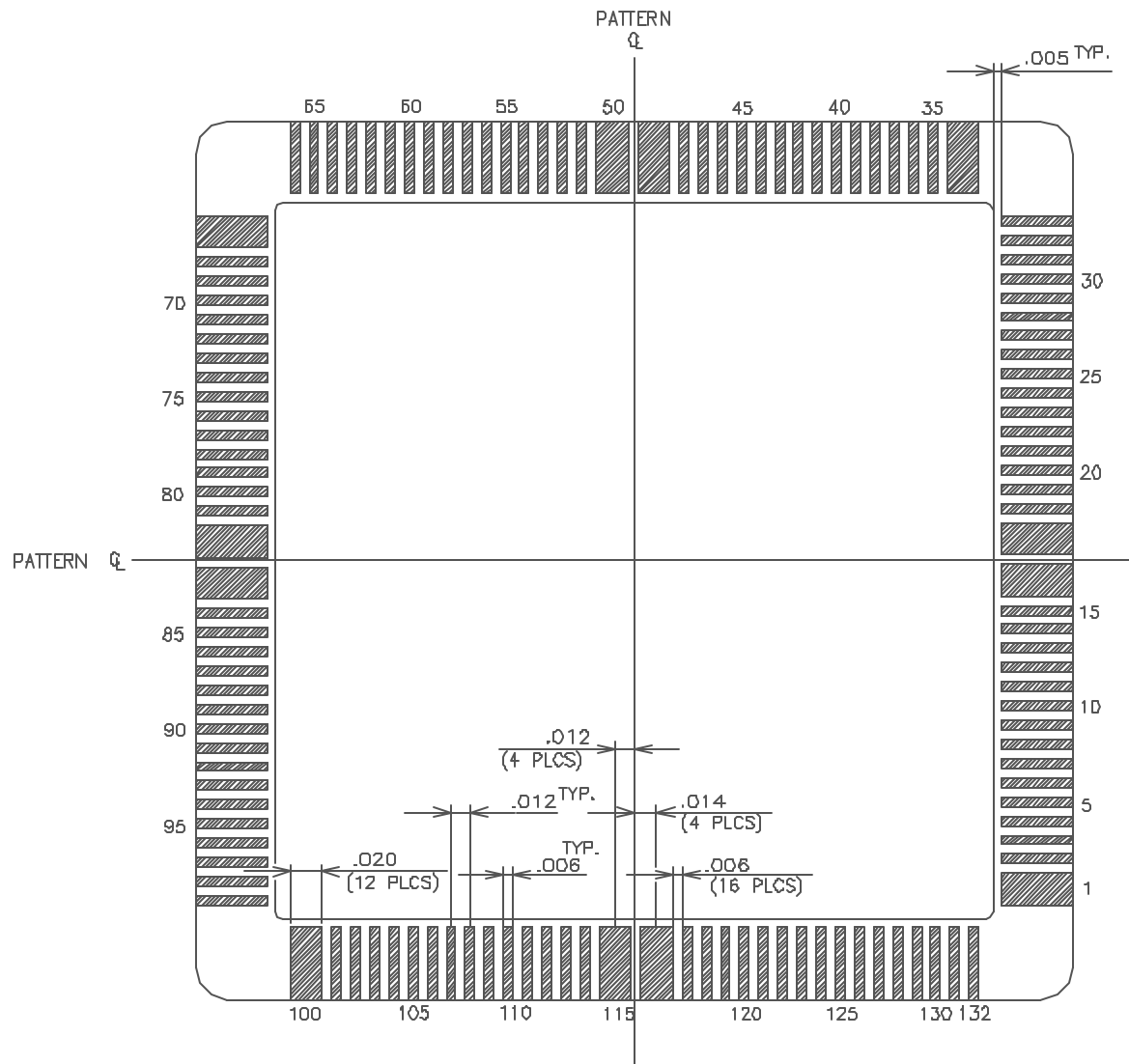




# SSM P/N CPG13213



BONDING PATTERN

MODIFICATION					NAME 132 PIN GRID ARRAY PACKAGE	TOLERANCE UNLESS OTHERWISE SPECIFIED	DRAWN T.I	CHECKED H.S/K.M	APPROVED T.A	DATE JUL 4 '96
					SCALE 2D/1	MATERIAL				
						THIS IS ALE PRODUCT				
	CHANGED	DATE	DRAWN	CHECKED	APPROVED		KYOCERA CORPORATION KYOTO JAPAN	DRAWING NO. KD-P96686	SHEET 2/3	



